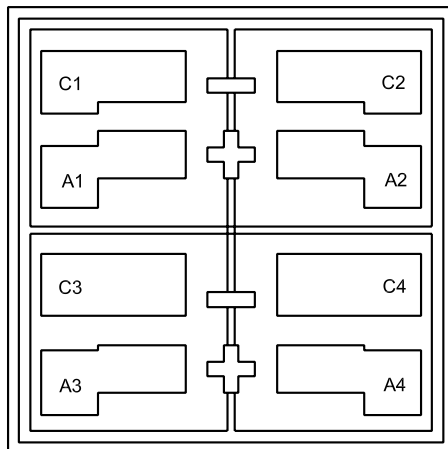


PROCESS DETAILS

Die Size	25 x 25 MILS
Die Thickness	6.0 MILS
Anode 1, 2, 3, 4 Bonding Pad Area	3.5 x 4.0 MILS
Cathode 1, 2, 3, 4 Bonding Pad Area	3.5 x 4.0 MILS
Top Side Metalization	Al - 12,000Å
Back Side Metalization	Au - 5,000Å

GEOMETRY



R0

GROSS DIE PER 3 INCH WAFER

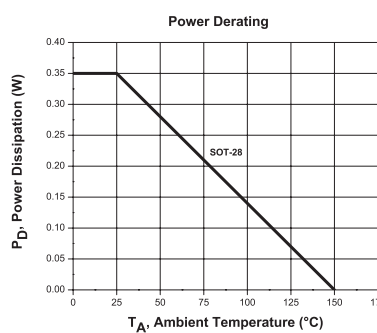
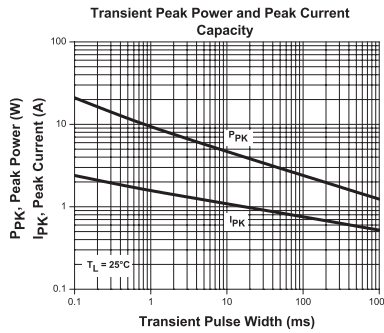
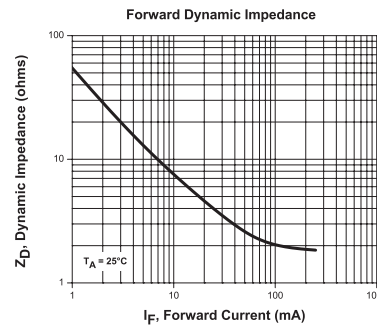
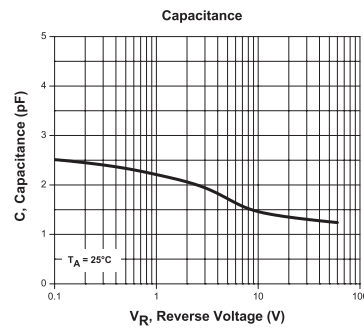
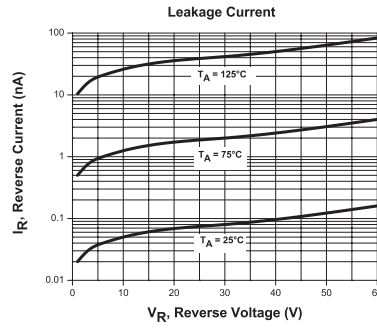
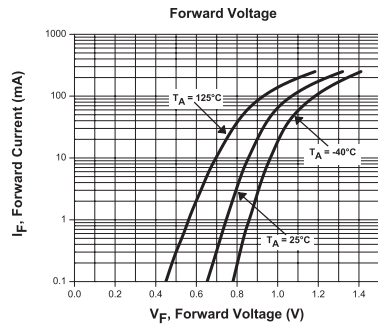
10,000

PRINCIPAL DEVICE TYPES

CMEDA-6i

145 Adams Avenue
Hauppauge, NY 11788 USA
Tel: (631) 435-1110
Fax: (631) 435-1824
www.centalsemi.com

R1 (28-August 2006)



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